

## 1A Driver Transistor Built-In, Step-Up DC/DC Converters

### GENERAL DESCRIPTION

The XC9128/XC9129 series are synchronous step-up DC/DC converters with a 0.2Ω (TYP.) N-channel driver transistor and a synchronous 0.2Ω (TYP.) P-channel switching transistor built-in. A highly efficient and stable current can be supplied up to 1.0A by reducing ON resistance of the built-in transistors. With a high switching frequency of 1.2MHz, a small inductor is selectable making the series ideally suited for applications requiring low profile or space saving solutions. With the MODE pin, the series provides mode selection of PWM control or PFM/PWM automatic switching control. In the PWM/PFM automatic switching mode, the series switches from PWM to PFM to reduce switching loss when load current is small. When load current is large, the series switches automatically to the PWM mode so that high efficiency is achievable over a wide range of load conditions. The series also provides small output ripple from light to large loads by using the built-in circuit which enables the smooth transition between PWM and PFM. When a voltage higher than the input voltage is applied to the output during shut-down, the input and the output become isolated making it possible for the IC to work in parallel with the likes of an AC adaptor.

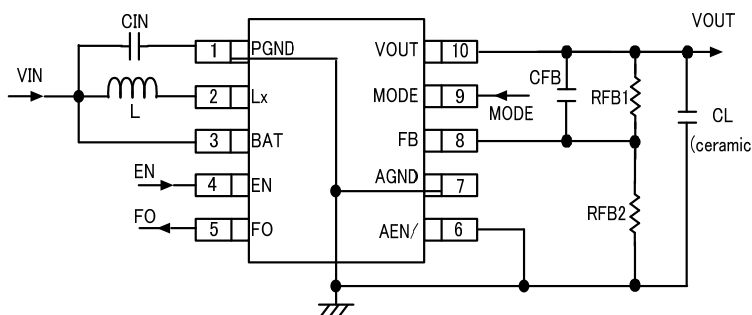
### APPLICATIONS

- Digital audio equipment
- Digital cameras, Video equipment
- Computer Mice
- Various multi-function power supplies using alkali cells (1 to 3 cells), nickel hydride batteries, or single lithium cells

### FEATURES

- High Efficiency, Large Current Step-Up Converter**
- Output Current** : 150mA@V<sub>OUT</sub>=3.3V, V<sub>IN</sub>=0.9V  
500mA@V<sub>OUT</sub>=3.3V, V<sub>IN</sub>=1.8V
- Input Voltage Range** : 0.8V~6.0V
- Output Voltage Setting Range** : 1.8V~5.3V (Externally set)  
Set up freely with a reference voltage supply of 0.45V (±0.01V) & external components
- Oscillation Frequency** : 1.2MHz (Fixed oscillation frequency accuracy ±15%)
- Input Current** : 1.0A
- Maximum Current Limit Control** : 1.2A (MIN.), 2.0A (MAX.)  
: PWM, PWM/PFM control externally selectable
- High Speed Transient Response** : 100mV @ V<sub>OUT</sub>=3.3V, V<sub>IN</sub>=1.8V, I<sub>OUT</sub>=10mA→100mA
- Protection Circuits** : Thermal shutdown  
: Integral latch method (Over current limit)  
: 5ms (TYP.) internally set
- Soft-Start Time** : 5ms (TYP.) internally set
- Ceramic Capacitor Compatible**
- Adaptor Enable Function**
- Packages** : MSOP-10, USP-10B, SOP-8
- Flag Output (FO)** : Open-drain output

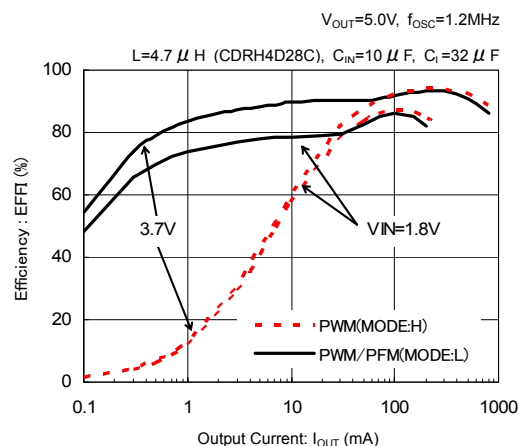
### TYPICAL APPLICATION CIRCUIT



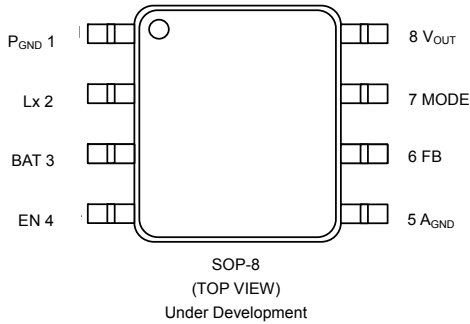
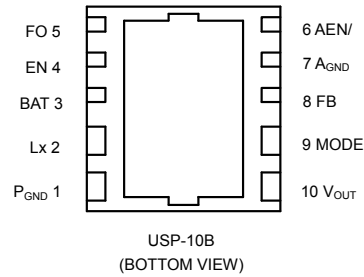
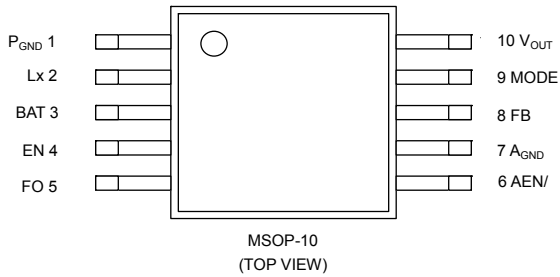
### TYPICAL PERFORMANCE CHARACTERISTICS

Efficiency vs. Output Current

XC9128B45CDx



## PIN CONFIGURATION



## PIN ASSIGNMENT

PIN NUMBER			PIN NAME	FUNCTION
MSOP-10*	USP-10B *	SOP-8 **		
1	1	1	PGND	Power Ground
2	2	2	Lx	Output of Internal Power Switch
3	3	3	BAT	Battery Input
4	4	4	EN	Chip Enable
5	5	-	FO	Flag Output
6	6	-	AEN/	Adaptor Enable
7	7	5	AGND	Analog Ground
8	8	6	FB	Output Voltage Monitor
9	9	7	MODE	Mode Switch
10	10	8	VOUT	Output Voltage

\* For MSOP-10 and USP-10B packages, please short the GND pins (pins 1 and 7).

\*The dissipation pad for the USP-10B package should be solder-plated following the recommended mount pattern and metal masking so as to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the Ground pins (pins 1 and 7).

\*\* For SOP-8 package, please short the GND pins (pins 1 and 5).

## FUNCTION CHART

### 1. EN, AEN/ Pin Function

EN PIN	AEN/ PIN	IC OPERATIONAL STATE	SOFT-START FUNCTION
L→H	L	Operation	Available
H	H→L	Operation	Not Available
H	H	Step-Up Operation Shut-Down	-
L	L	Shut-Down	-
L	H	Shut-Down	-

\* Do not leave the EN and AEN/ Pins open.

### 2. MODE Pin Function

MODE PIN	FUNCTION
H	PWM Control
L	PWM/PFM Automatic Switching Control

\* Do not leave the MODE Pin open.

## PRODUCT CLASSIFICATION

### Ordering Information

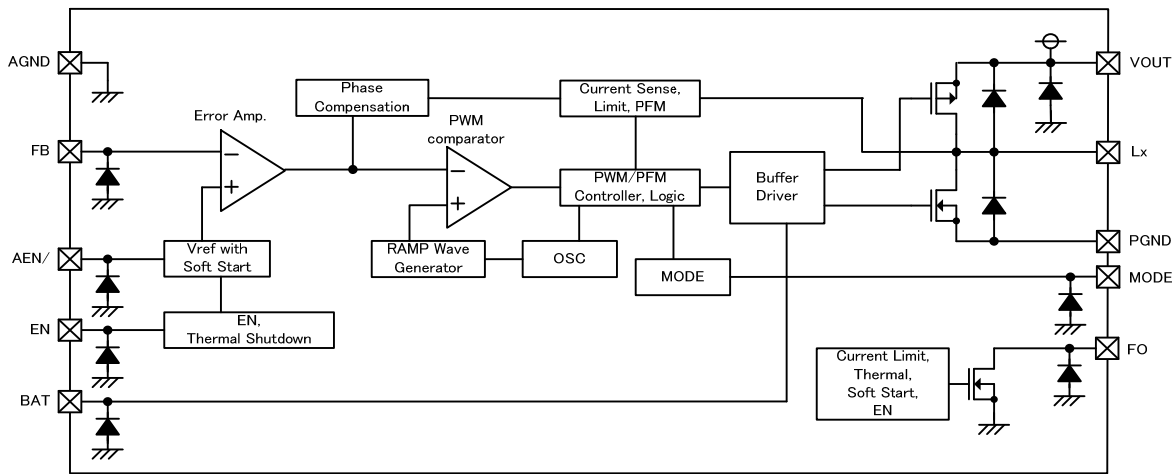
XC9128①②③④⑤⑥···· MSOP-10, USP-10B

XC9129①②③④⑤⑥···· SOP-8 (Under Development)

DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION
①	Transistor Built-In, Output Voltage Freely Set (FB voltage), Integral Protection Type	B	: With integral protection
		D	: Without integral protection
②③	Reference Voltage	45	: Fixed reference voltage 0.45V ②=4, ③=5
④	Oscillation Frequency	C	: 1.2MHz
⑤	Packages	A	: MSOP-10
		D	: USP-10B
		S	: SOP-8
⑥	Device Orientation	R	: Embossed tape, standard feed
		L	: Embossed tape, reverse feed

## BLOCK DIAGRAM

XC9128 Series



XC9129 Series

The AEN/ Pin and FO Pin are not connected to the circuit in the block diagram of the XC9129 series.

## ABSOLUTE MAXIMUM RATINGS

Ta=25°C

PARAMETER	SYMBOL	RATINGS	UNITS
V <sub>OUT</sub> Pin Voltage	V <sub>OUT</sub>	- 0.3~6.5	V
AEN/ Pin Voltage	V <sub>AEN/</sub>	- 0.3~6.5	V
FO Pin Voltage	V <sub>FO</sub>	- 0.3~6.5	V
FO Pin Current	I <sub>FO</sub>	10	mA
FB Pin Voltage	V <sub>FB</sub>	- 0.3~6.5	V
BAT Pin Voltage	V <sub>BAT</sub>	- 0.3~6.5	V
MODE Pin Voltage	V <sub>MODE</sub>	- 0.3~6.5	V
EN Pin Voltage	V <sub>EN</sub>	- 0.3~6.5	V
L <sub>x</sub> Pin Voltage	V <sub>Lx</sub>	- 0.3~V <sub>OUT</sub> +0.3	V
L <sub>x</sub> Pin Current	I <sub>Lx</sub>	2000	mA
Power Dissipation	MSOP-10	350 <sup>(*)</sup>	mW
	USP-10B	150	
	SOP-8 (Under Development)	300	
Operating Temperature Range	T <sub>opr</sub>	- 40~+85	°C
Storage Temperature Range	T <sub>stg</sub>	- 55~+125	°C

\*1: When implemented on a PCB.

## ELECTRICAL CHARACTERISTICS

XC9128/XC9129 Series

Topr=25 °C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
Input Voltage	V <sub>IN</sub>	-	-	-	6.0	V	-
FB Voltage	V <sub>FB</sub>	V <sub>OUT</sub> =V <sub>IN</sub> =3.3V, V <sub>PULL</sub> =3.3V, V <sub>FO</sub> =0V Voltage to start oscillation during FB=0.46V → 0.44V	0.44	0.45	0.46	V	
Output Voltage Setting Range	V <sub>OUTSET</sub>	-	1.8	-	5.3	V	
Operation Start Voltage	V <sub>ST1</sub>	Connect to external components, R <sub>L</sub> =1kΩ	-	-	0.8	V	
		Connect to external components, R <sub>L</sub> =33Ω	-	-	0.9 <sup>(*)1</sup>	V	
Oscillation Start Voltage	V <sub>ST2</sub>	Voltage to start oscillation during V <sub>IN</sub> =0V → 1V	-	0.8	-	V	
Operation Hold Voltage	V <sub>HLD</sub>	Connect to external components, R <sub>L</sub> =1kΩ	-	0.7	-	V	
Supply Current 1	I <sub>DD1</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, FB=V <sub>FB</sub> ×0.9	-	3	6	mA	
Supply Current 2	I <sub>DD2</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V FB=V <sub>FB</sub> ×1.1 (Oscillation stops), MODE=0V	-	30	80	μA	
Input Pin Current	I <sub>BAT</sub>	V <sub>IN</sub> =3.3V, V <sub>OUT</sub> =1.8V, EN=0V	-	2	10	μA	
Stand-by Current	I <sub>STB</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, EN=0V	-	2	10	μA	
Oscillation Frequency	f <sub>OSC</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0V, FB=V <sub>FB</sub> ×0.9	1.02	1.20	1.38	MHz	
Maximum Duty Cycle	MAXDTY	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0V, FB=V <sub>FB</sub> ×0.9	85	92	96	%	
Minimum Duty Cycle	MINDTY	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0V, FB=V <sub>FB</sub> ×1.1	-	-	0	%	
PFM Switching Current	I <sub>PFM</sub>	Connect to external components, MODE=0V, I <sub>OUT</sub> =10mA	-	250	400	mA	
Efficiency <sup>(*)2</sup>	EFF1	Connect to external components, I <sub>OUT</sub> =100mA	-	93	-	%	
Lx SW "Pch" ON Resistance	R <sub>LxP</sub>	V <sub>IN</sub> =V <sub>OUT</sub> +50mV, FB=V <sub>FB</sub> ×1.1, MODE=0V <sup>(*)3</sup>	-	0.20	0.35 <sup>(*)1</sup>	Ω	
Lx SW "Nch" ON Resistance	R <sub>LxN</sub>	V <sub>IN</sub> =3.3V, V <sub>OUT</sub> =3.3V, Lx=50mV, FB=V <sub>FB</sub> ×0.9 <sup>(*)4</sup>	-	0.20 <sup>(*)1</sup>	0.35 <sup>(*)1</sup>	Ω	
Lx Leak Current	I <sub>LXL</sub>	V <sub>OUT</sub> =V <sub>LX</sub> =V <sub>IN</sub> =3.3V, EN=0V, FB=0V, MODE=0V	-	1	-	μA	
Current Limit <sup>(*)5</sup>	I <sub>LIM</sub>	V <sub>OUT</sub> >2.5V	1.2	1.5	2.0	A	
Integral Latch Time <sup>(*)6</sup>	T <sub>LAT</sub>	Time to stop oscillation during R <sub>L</sub> =33Ω → 3.3Ω, V <sub>FO</sub> =L → H	-	3.5	-	ms	
Soft-Start Time 1	T <sub>SS1</sub>	Time to start oscillation during V <sub>EN</sub> =0V → V <sub>IN</sub> at V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0V, FB=V <sub>FB</sub> ×0.95	1.7	5.3	10.5	ms	
Soft-Start Time 2	T <sub>SS2</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0V, FB> V <sub>FB</sub> ×0.95 Time to start oscillation during V <sub>AEN</sub> =V <sub>IN</sub> →0V.	-	0.02	0.04	ms	
Soft-Start Time 3	T <sub>SS3</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0V, FB<V <sub>FB</sub> ×0.8 Time to start oscillation during V <sub>AEN</sub> =V <sub>IN</sub> →0V	1.7	5.3	10.5	ms	
Thermal Shutdown Temperature	T <sub>TSD</sub>	-	-	150	-	°C	-
Hysteresis Width	T <sub>HYS</sub>	-	-	20	-	°C	-
Output Voltage Drop Protection <sup>(*)6</sup>	LVP	V <sub>IN</sub> =3.3V Voltage to stop oscillation during V <sub>OUT</sub> =1.56V→1.3V	1.3	1.48	1.56	V	
FO Output Current <sup>(*)7</sup>	I <sub>FO_OUT</sub>	V <sub>IN</sub> =V <sub>OUT</sub> =3.3V, V <sub>FO</sub> =0.25V	1.3	1.7	2.2	mA	
FO Leak Current <sup>(*)7</sup>	I <sub>FO_Leak</sub>	V <sub>IN</sub> = V <sub>OUT</sub> =3.3V, EN=0V, V <sub>FO</sub> =1V	-	0	1	μA	

## ELECTRICAL CHARACTERISTICS (Continued)

●XC9128/XC9129 Series (Continued)

Topr=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT
EN "H" Voltage	VENH	$V_{IN} = V_{OUT} = 3.3V, V_{FO} = 0V$ Voltage to start oscillation during $FB = V_{FB} \times 0.9$ , $EN = 0.2V \rightarrow 0.65V$	0.65	-	-	V	
EN "L" Voltage	VENL	$V_{IN} = V_{OUT} = 3.3V, V_{FO} = 0V$ Voltage to stop oscillation during $FB = V_{FB} \times 0.9$ , $EN = 0.65V \rightarrow 0.2V$	-	-	0.2	V	
MODE "H" Voltage	VMODEH	$I_{OUT} = 10mA$ , Voltage operates at PWM control	0.65	-	-	V	
MODE "L" Voltage	VMODEL	$I_{OUT} = 10mA$ , Voltage operates at PFM control	-	-	0.2	V	
AEN/ Voltage <sup>(7)</sup>	VAEN/	$V_{IN} = V_{OUT} = 3.3V, V_{FO} = 0V$ Voltage to start oscillation during $AEN = 0.9V \rightarrow 0.7V$	0.7	0.8	0.9	V	
EN "H" Current	IENH	$V_{OUT} = FB = EN = 6.0V$	-	-	0.1	$\mu A$	
EN "L" Current	IENL	$V_{OUT} = FB = 6.0V, EN = 0V$	-0.1	-	-	$\mu A$	
MODE "H" Current	IMODEH	$V_{OUT} = FB = MODE = 6.0V$	-	-	0.1	$\mu A$	
MODE "L" Current	IMODEL	$V_{OUT} = FB = 6.0V, MODE = 0V$	-0.1	-	-	$\mu A$	
AEN/ "H" Current <sup>(7)</sup>	IAEN/H	$V_{OUT} = FB = AEN/ = 6.0V$	-	-	0.1	$\mu A$	
AEN/ "L" Current <sup>(7)</sup>	IAEN/L	$V_{OUT} = 6.0V, EN = 0V, AEN/ = 0V$	-0.1	-	-	$\mu A$	
FB "H" Current	IFBH	$V_{OUT} = FB = 6.0V$	-	-	0.1	$\mu A$	
FB "L" Current	IFBL	$V_{OUT} = 6.0V, FB = 0V$	-0.1	-	-	$\mu A$	

Conditions: Unless otherwise stated,

operate at  $V_{OUT} = 3.3V, V_{IN} = 1.8V, EN = 3.3V, FB = 0V, MODE = 3.3V, V_{FO} = 3.3V, V_{pull} = 3.3V, AEN/ = 0V$

External Components:  $R_{FB1} = 270k\Omega, R_{FB2} = 43k\Omega, C_{FB} = 12pF, L = 4.7 \mu H$  (LTF5022 TDK)

$C_{L1} = 22 \mu F$  (ceramic),  $C_{L2} = 10 \mu F$  (ceramic),  $C_{IN} = 10 \mu F$  (ceramic)

NOTE:

\*1 : Designed value

\*2 : Efficiency =  $\{(output\ voltage) \times (output\ current)\} \div \{(input\ voltage) \times (input\ current)\} \times 100$

\*3 :  $L_x$  SW "P-ch" ON resistance =  $(V_{Lx} - V_{OUT} \text{ pin test voltage}) \div 100mA$

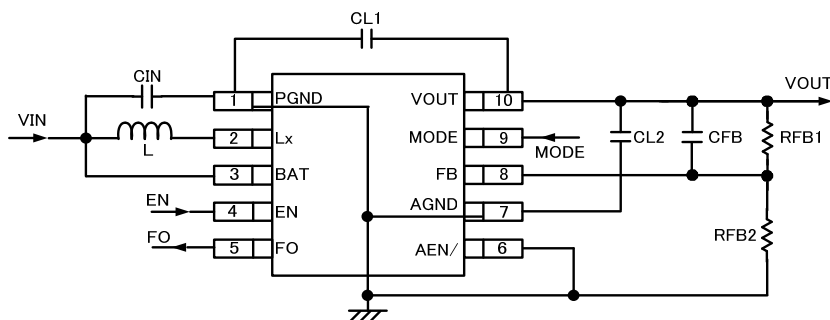
\*4 : Testing method of  $L_x$  SW "N-ch" ON resistance is stated at test circuits.

\*5 : Current flowing through the Nch driver transistor is limited.

\*6 : The XC9128D series does not have integral protection. This is only available with the XC9128B series.

\*7 : The XC9129 series does not have FO or AEN/ pins. These are only available with the XC9128 series.

## TYPICAL APPLICATION CIRCUIT



### <Output Voltage Setting>

Output voltage can be set by adding external split resistors. Output voltage is determined by the following equation, based on the values of RFB1 and RFB2. The sum of RFB1 and RFB2 should normally be 500kΩ or less.

$$V_{OUT} = 0.45 \times (R_{FB1} + R_{FB2}) / R_{FB2}$$

The value of CFB, speed-up capacitor for phase compensation, should be  $f_{ZFB} = 1 / (2 \times \pi \times C_{FB1} \times R_{FB1})$  which is in the range of 10 kHz to 50 kHz. Adjustments are depending on application, inductance (L), load capacitance (CL) and dropout voltage.

### [Example of calculation]

When RFB1=270k , RFB2=43k ,

$$V_{OUT1} = 0.45 \times (270k + 43k) / 43k = 3.276V$$

### [Typical example]

VOUT (V)	RFB1 (k )	RFB2 (k )	CFB (pF)
1.8	300	100	10
2.5	270	59	12
3.3	270	43	12
5.0	180	17.8	15

### [External Components]

1.2MHz:

L : 4.7 μH (CDRH4D28C SUMIDA)

CL1: 22 μF (ceramic)

CL2: 10 μF (ceramic)

CIN: 10 μF (ceramic)

\* For CL, use output capacitors of 30 μF or more. (Ceramic capacitor compatible)

\* If using Tantalum or Electrolytic capacitors please be aware that ripple voltage will be higher due to the larger ESR (Equivalent Series Resistance) values of those types of capacitors. Please also note that the IC's operation may become unstable with such capacitors so we recommend that you fully check actual performance.

## OPERATIONAL EXPLANATION

The XC9128/XC9129 series consists of a reference voltage source, ramp wave circuit, error amplifier, PWM comparator, phase compensation circuit, N-channel driver transistor, P-channel synchronous rectification switching transistor and current limiter circuit. The series compares, using the error amplifier, the internal reference voltage to the FB pin with the voltage feedback via resistors RFB1 and RFB2. Phase compensation is performed on the resulting error amplifier output, to input a signal to the PWM comparator to determine the turn-on time of the N-ch driver transistor during PWM operation. The PWM comparator compares, in terms of voltage level, the signal from the error amplifier with the ramp wave from the ramp wave circuit, and delivers the resulting output to the buffer driver circuit to cause the Lx pin to output a switching duty cycle. This process is continuously performed to ensure stable output voltage. The current feedback circuit monitors the N-channel driver transistor's turn-on current for each switching operation, and modulates the error amplifier output signal to provide multiple feedback signals. This enables a stable feedback loop even when a low ESR capacitor, such as a ceramic capacitor, is used, ensuring stable output voltage.

### <Reference Voltage Source>

The source provides the reference voltage to ensure stable output of the DC/DC converter.

### <Ramp Wave Circuit>

The ramp wave circuit determines switching frequency. The frequency is fixed internally at 1.2MHz. The Clock generated is used to produce ramp waveforms needed for PWM operation, and to synchronize all the internal circuits.

### <Error Amplifier>

The error amplifier is designed to monitor output voltage. The amplifier compares the reference voltage with the feedback voltage divided by the internal resistors (RFB1 and RFB2). When the FB pin is lower than the reference voltage, output voltage of the error amplifier increases. The gain and frequency characteristics of the error amplifier are optimized internally.

### < Maximum Current Limit>

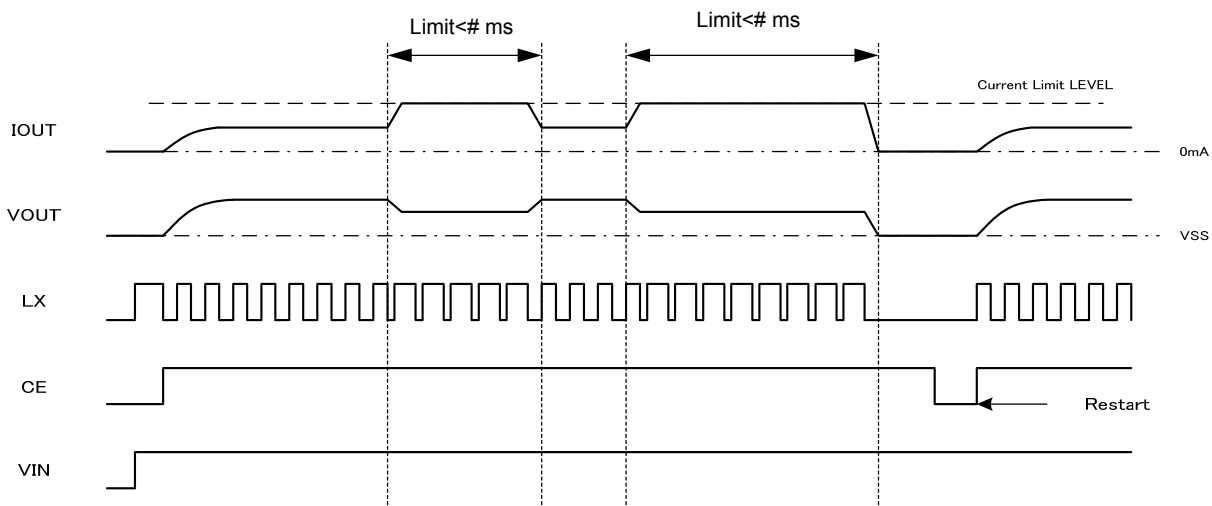
The current limiter circuit monitors the maximum current flowing through the N-ch driver transistor connected to the Lx pin, and features a combination of the current limit and latch function.

- ① When the driver current is greater than a specific level (equivalent to peak coil current), the maximum current limit function starts to operate and the pulses from the Lx pin turn off the N-ch driver transistor at any given time.
- ② When the driver transistor is turned off, the limiter circuit is then released from the maximum current limit detection state.
- ③ At the next pulse, the driver transistor is turned on. However, the transistor is immediately turned off in the case of an over current state.
- ④ When the over current state is eliminated, the IC resumes its normal operation.

The XC9128B/XC9129B series waits for the over current state to end by repeating the steps ① through ③. If an over current state continues for several ms and the above three steps are repeatedly performed, the IC performs the function of latching the OFF state of the Nch driver transistor, and goes into operation suspension mode. After being put into suspension mode, the IC can resume operation by turning itself off once and then re-starting via the EN pin, or by restoring power to the VIN pin.

The XC9128D/XC9129D series does not have this latch function, so operation steps ① through ③ repeat until the over current state ends.

Integral latch time may be released from a over current detection state because of the noise. Depending on the state of a substrate, it may result in the case where the latch time may become longer or the operation may not be latched. Please locate an input capacitor as close as possible.





## OPERATIONAL EXPLANATION (Continued)

### <Thermal Shutdown>

For protection against heat damage, the thermal shutdown function monitors chip temperature. When the chip's temperature reaches 150°C (TYP.), the thermal shutdown circuit starts operating and the driver transistor will be turned off. At the same time, the output voltage decreases. When the temperature drops to 130°C (TYP.) after shutting off the current flow, the IC performs the soft start function to initiate output startup operation.

### <MODE>

The MODE pin operates in PWM mode by applying a high level voltage and in PFM/PWM automatic switching mode by applying a low level voltage.

### <Shut-Down>

The IC enters chip disable state by applying low level voltage to the EN pin. At this time, the P-ch synchronous switching transistor turns on when  $V_{IN} > V_{OUT}$  and vice versa the transistor turns off when  $V_{IN} < V_{OUT}$ .

### <Adaptor Enable>

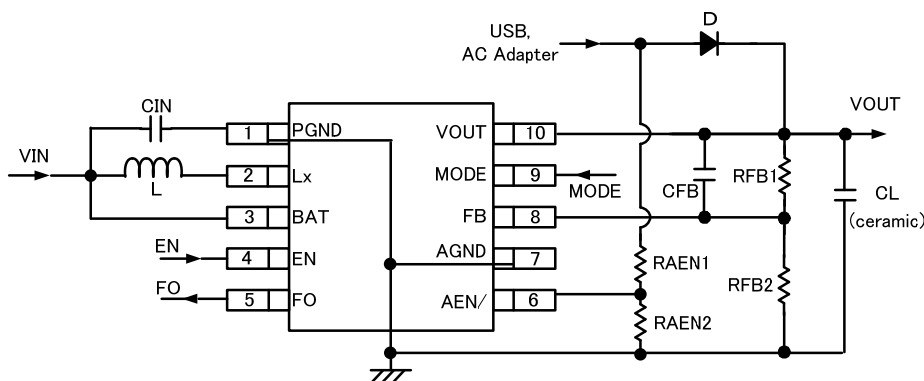
While using step-up DC/DC converters in parallel with an added power source such as AC adaptors, the circuit needs the step-up DC/DC converter to be transient-efficient for sustaining output voltage in case the added power source runs down. The AEN/ pin voltage determines whether the added power source is supplied or not so that high-speed following operation is possible. The IC starts operating although the driver transistor is off when a high level voltage is applied to the AEN/ pin after a high level voltage is also applied to the EN pin. If the AEN/ pin voltage changes from high level to low level while the EN pin sustains a high level voltage, the step-up operation starts with high-speed following mode (without soft-start).

### <Error Flag >

The FO pin becomes high impedance during over current state, over temperature state, soft-start period, and shut-down period.

## NOTE ON USE

1. Please do not exceed the stated absolute maximum ratings values.
2. The DC/DC converter / controller IC's performance is greatly influenced by not only the IC's characteristics, but also by those of the external components. Care must be taken when selecting the external components.
3. Make sure that the PCB GND traces are as thick as possible, as variations in ground potential caused by high ground currents at the time of switching may result in instability of the IC.
4. Please mount each external component as close to the IC as possible and use thick, short traces to reduce the circuit impedance.
5. When the device is used in high step-up ratio, the current limit function may not work during excessive load current. In this case, the maximum duty cycle limits maximum current.
6. When the adaptor enable function is used in the below circuit, please use a diode with low reverse bias current. The sum of  $R_{AEN1}$ 's and  $R_{AEN2}$ 's resistance should be set to manage the reverse bias current.



## NOTE ON USE (Continued)

### 7. P-ch synchronous switching transistor operation

The parasitic diode of the P-ch synchronous transistor is placed between Lx (anode) and V<sub>OUT</sub> (cathode), so that the power line can not be turned off from Lx to V<sub>OUT</sub>. On the other hand, the power line switch from V<sub>OUT</sub> to Lx is shown in the table below.

EN Pin	AEN/Pin	P-ch Synchronous Switch Transistor Operation
H	H	OFF
H	L	Switching
L	H	OFF
L	L	Undefined

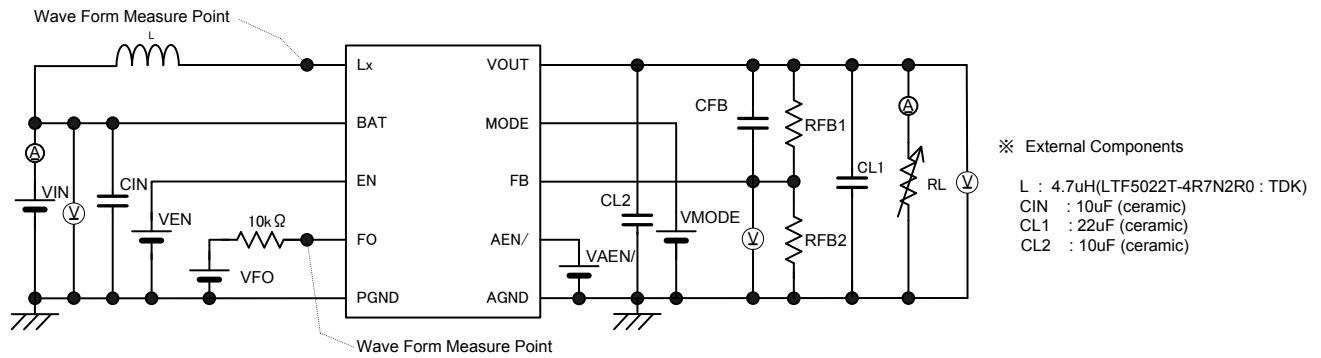
With the XC9128B/XC9129B series, when step-up operation stops as a result of the latch condition working when the maximum current limit level is reached, the synchronous P-ch transistor will remain ON.

With the XC9128B/XC9129B series, when step-up operation stops as a result of the latch condition working when the low output voltage protection level is reached, the synchronous P-ch transistor will remain ON.

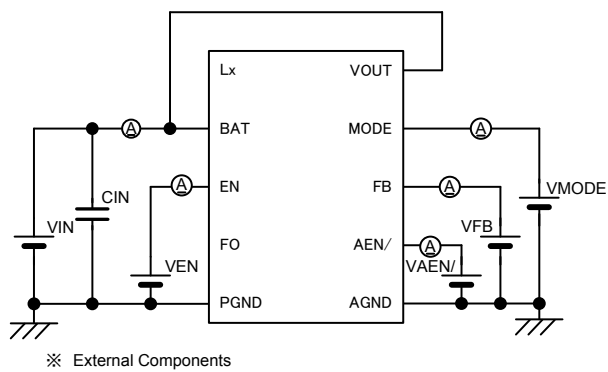
8. The maximum current limiter controls the limit of the N-ch driver transistor by monitoring current flow. This function does not limit the current flow of the P-ch synchronous transistor.
9. The integral latch time of the XC9128B/XC9129B series could be released from the maximum current detection state as a result of board mounting conditions. This may extend integral latch time or the level required for latch operation to function may not be reached. Please connect the output capacitor as close to the IC as possible.
10. When used in small step-up ratios, the device may skip pulses during PWM control mode.

# TEST CIRCUITS

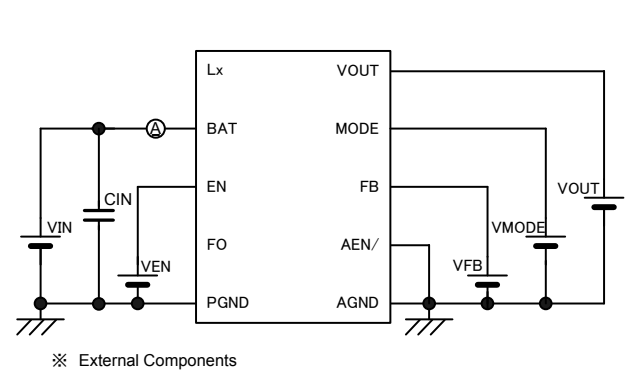
< Circuit No.1 >



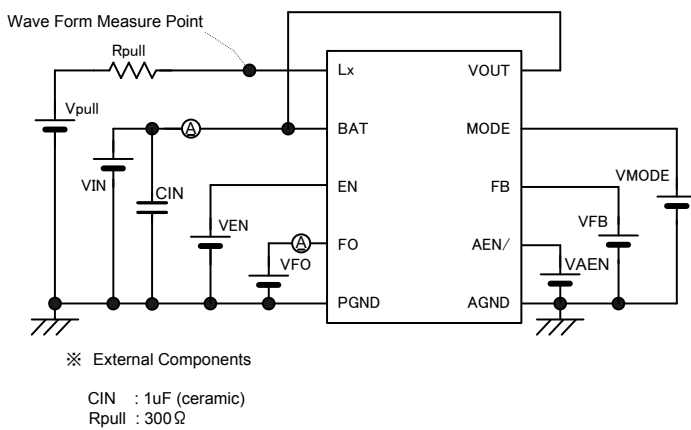
< Circuit No.2 >



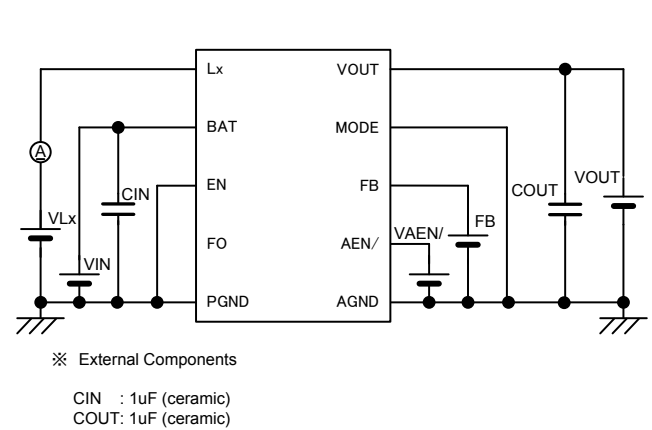
< Circuit No.3 >



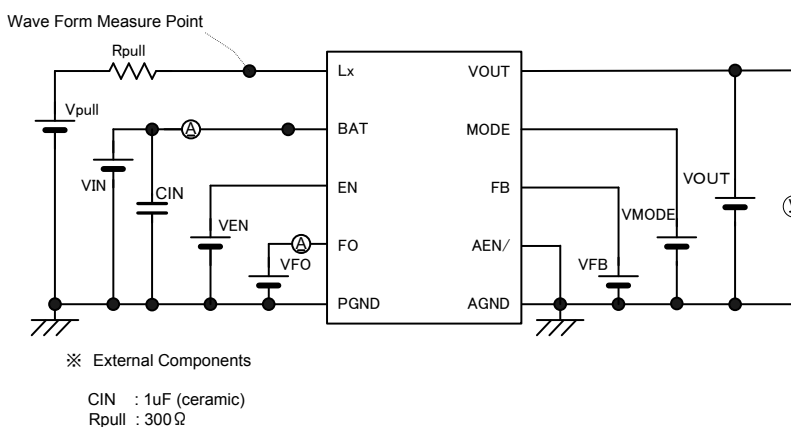
< Circuit No.4 >



< Circuit No.5 >

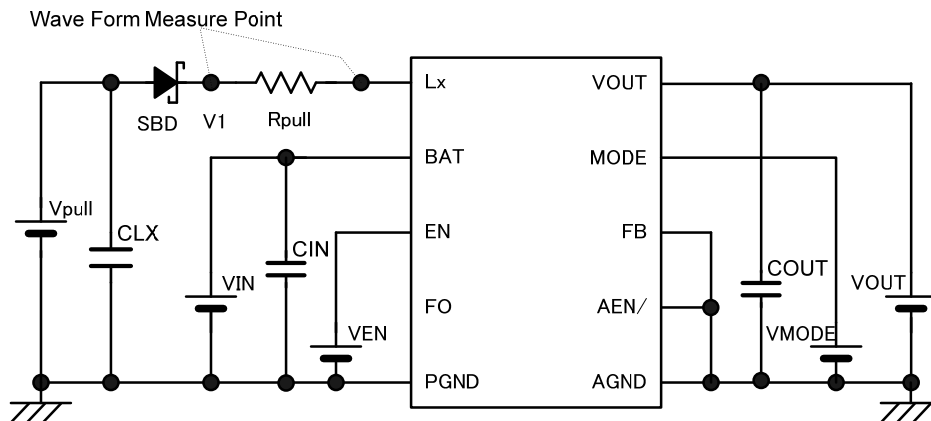


< Circuit No.6 >



## TEST CIRCUITS (Continued)

### <Circuit No.7 >



#### ※ External Components

- CIN : 1 $\mu$ F (ceramic)
- COUT : 1 $\mu$ F (ceramic)
- SBD : XBS304S17(TOREX)
- Rpull : 0.5 $\Omega$

#### Measurement method for ON resistance of the Lx switch

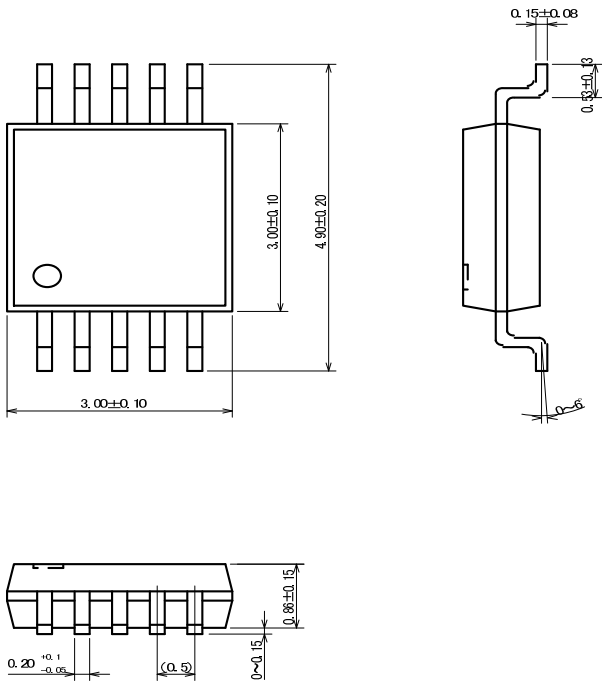
Using the layout of circuit No.7 above, set the LX pin voltage to 50mV by adjusting the  $V_{pull}$  voltage whilst the N-ch driver transistor is turned on. Then, measure the voltage difference between both ends of  $R_{pull}$ . ON Resistance is calculated by using the following formula:

$$R_{LXN} = 0.05 \div ((V1 - 0.05) \div 0.5)$$

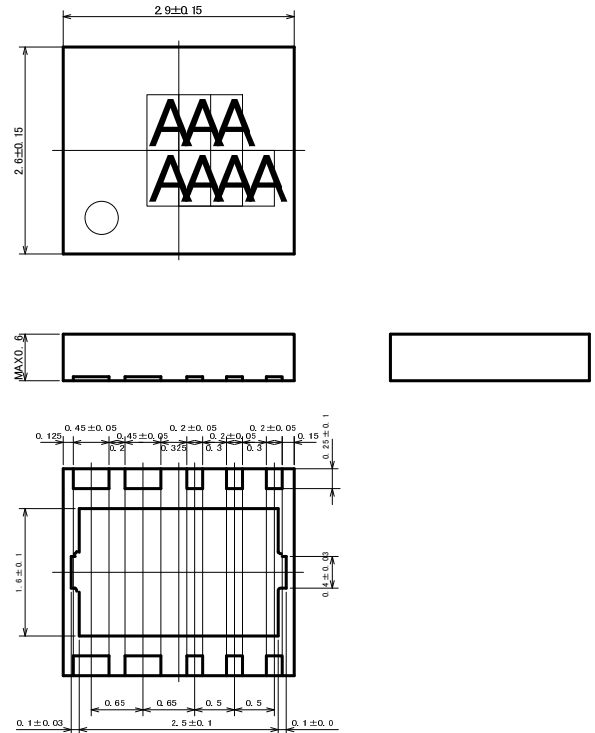
where  $V1$  is a voltage between SBD and  $R_{pull}$ , measured by an oscilloscope.

# PACKAGING INFORMATION

MSOP-10

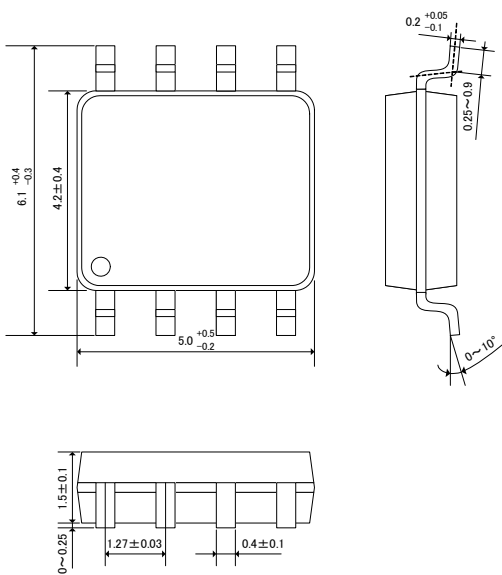


● USP-10B



● SOP-8

(unit : mm)



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